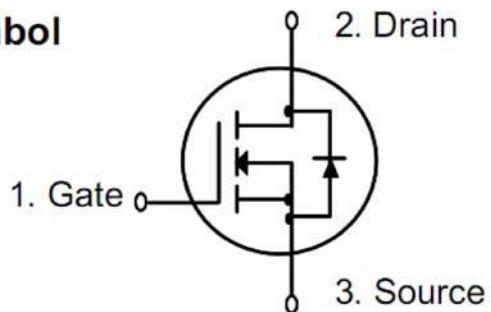
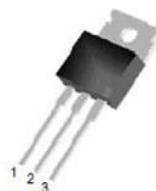


N-Channel MOSFET
Features

- $R_{DS(on)}$ (Max 0.008 Ω)@ $V_{GS}=10V$
- Gate Charge (Typical 80 nC)
- Maximum Junction Temperature Range (175 °C)

Symbol

TO-220 AB/3

Absolute Maximum Ratings

| Symbol | Parameter | Value | Units |
|-----------|--|----------------------|-------|
| V_{DSS} | Drain to Source Voltage | 80 | V |
| I_D | Continuous Drain Current(@ $T_C = 25$ °C) | 100 | A |
| | Continuous Drain Current(@ $T_C = 100$ °C) | 75 | A |
| I_{DM} | Drain Current Pulsed | 300 ^{..1)} | A |
| V_{GS} | Gate to Source Voltage | ± 20 | V |
| E_{AS} | Single Pulsed Avalanche Energy | 1310 ^{..2)} | mJ |
| E_{AR} | Repetitive Avalanche Energy | 173 ^{..1)} | mJ |
| dv/dt | Peak Diode Recovery dv/dt | 70 ^{..3)} | V/ns |
| P_D | Total Power Dissipation(@ $T_C = 25$ °C) | 173 | W |
| | Derating Factor above 25 °C | 1.15 | W/°C |
| T_{STG} | Operating Junction Temperature | -55 ~ 175 | °C |
| T_J | Storage Temperature | 150 | °C |

Notes

^{1)..} Repeativity rating : pulse width limited by junction temperature

^{2)..} L = 0.32 mH, $I_{AS} = 100$ A, $V_{DD} = 50$ V, $R_G = 25 \Omega$, Starting $T_J = 25$ °C

^{3)..} $I_{SD} \leq 100$ A, $di/dt \leq 300$ A/us, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25$ °C

Thermal Characteristics

| Symbol | Parameter | Value | | | Units |
|-----------------|--|-------|------|------|-------|
| | | Min. | Typ. | Max. | |
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | - | - | 0.87 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient* | - | 0.5 | - | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | - | - | 62.5 | °C/W |

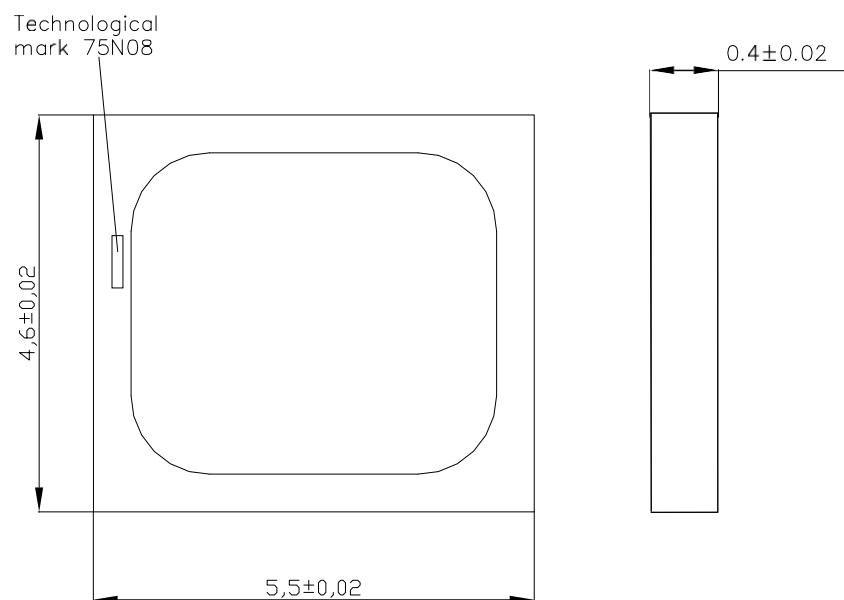
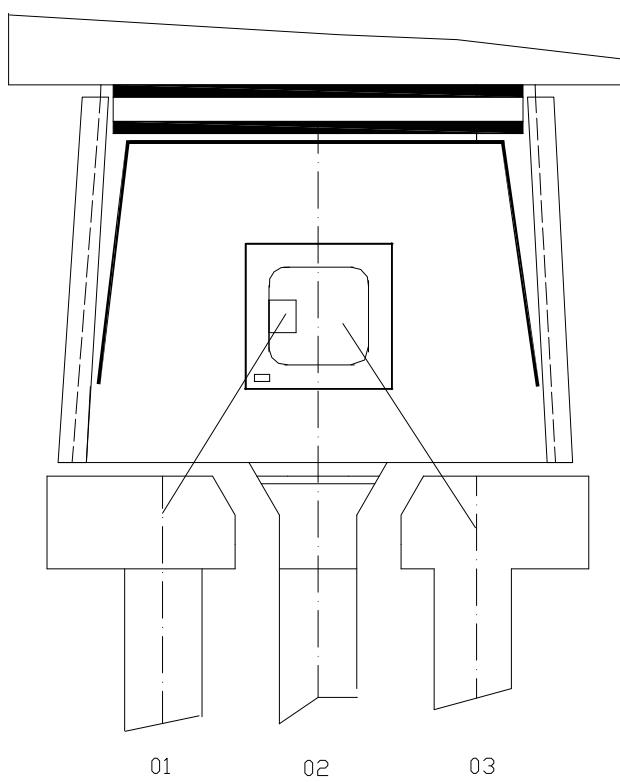
* When mounted on the minimum pad size recommended (PCB Mount)

Source-Drain Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|----------|---|---|-----|-----|-----|-------|
| I_S | Maximum Continuous Source-Drain Diode Forward Current | $I_S = 100 \text{ A}, V_{GS} = 0 \text{ V}$ | - | - | 100 | A |
| I_{SM} | Maximum Pulsed Source-Drain Diode Forward Current | | - | - | 380 | |
| V_{SD} | Diode Forward Voltage | - | - | 1.5 | V | |
| t_{rr} | Reverse Recovery Time | $I_S = 100 \text{ A}, V_{GS} = 0 \text{ V}, dI/dt = 100 \text{ A/us}$ | - | 90 | - | ns |
| Q_{rr} | Reverse Recovery Charge | | - | 250 | - | |

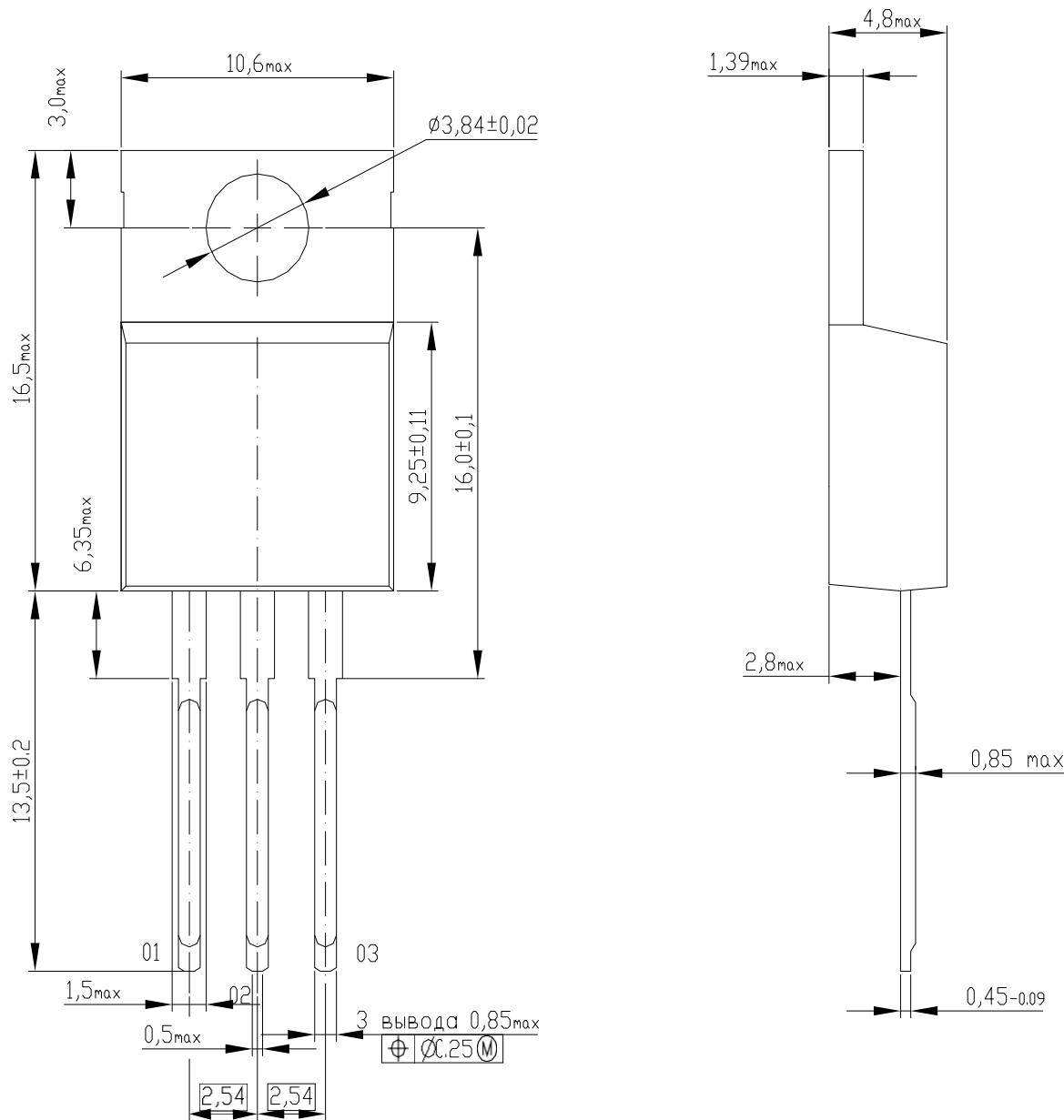
Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--|---|--|-----|------|-------|---------------------|
| Off Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$ | 80 | - | - | V |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | Breakdown Voltage Temperature coefficient | $I_D = 250 \mu\text{A}$, referenced to 25°C | - | 0.08 | - | V/ $^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{\text{DS}} = 80 \text{ V}$, $V_{\text{GS}} = 0 \text{ V}$ | - | - | 10 | μA |
| | | $V_{\text{DS}} = 64 \text{ V}$, $T_C = 125^\circ\text{C}$ | - | - | 100 | μA |
| I_{GSS} | Gate-Source Leakage, Forward | $V_{\text{GS}} = 20 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$ | - | - | 100 | nA |
| | Gate-source Leakage, Reverse | $V_{\text{GS}} = -20 \text{ V}$, $V_{\text{DS}} = 0 \text{ V}$ | - | - | -100 | nA |
| On Characteristics | | | | | | |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250 \mu\text{A}$ | 2.0 | - | 4.0 | V |
| $R_{\text{DS(ON)}}$ | Static Drain-Source On-state Resistance | $V_{\text{GS}} = 10 \text{ V}$, $I_D = 37.5 \text{ A}$ | - | - | 0.008 | Ω |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{\text{GS}} = 0 \text{ V}$, $V_{\text{DS}} = 25 \text{ V}$, $f = 1 \text{ MHz}$ | - | 2600 | 3380 | pF |
| C_{oss} | Output Capacitance | | - | 940 | 1220 | |
| C_{rss} | Reverse Transfer Capacitance | | - | 210 | 275 | |
| Dynamic Characteristics | | | | | | |
| $t_{\text{d(on)}}$ | Turn-on Delay Time | $V_{\text{DD}} = 40 \text{ V}$, $I_D = 100 \text{ A}$, $R_G = 25 \Omega$ Pulse Width $\leq 300\text{us}$, $Q > 50$ | - | 30 | 70 | ns |
| t_r | Rise Time | | - | 225 | 460 | |
| $t_{\text{d(off)}}$ | Turn-off Delay Time | | - | 165 | 340 | |
| t_f | Fall Time | | - | 155 | 320 | |
| Q_g | Total Gate Charge | $V_{\text{DS}} = 64 \text{ V}$, $V_{\text{GS}} = 10 \text{ V}$, $I_D = 100 \text{ A}$ | - | 80 | 105 | nC |
| Q_{gs} | Gate-Source Charge | | - | 15 | - | |
| Q_{gd} | Gate-Drain Charge(Miller Charge) | | - | 32 | - | |

Chip size**Package Chip**



Package Dimensions TO-220 AB/3



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